## Notice of References Cited

Application/Control No.

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Examiner

Samuel Broda

Applicant(s)/Patent Under
Reexamination
NGUYEN ET AL.

Art Unit
Page 1 of 1

## **U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	Α	US-6,064,982 A	05-2000	Puri, Deepak	705/27
	В	US-5,793,632 A	08-1998	Fad et al.	705/400
	С	US-5,539,652 A	07-1996	Tegethoff, Mauro V.	703/14
	D	US-			
	Ε	US-			
	F	US-			
	G	US-			
	Н	US-			
	_	US-			
	J	US-			
	К	US-			
	L	US-			
	М	US-			

## **FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	0					
	Р					
	Q					
	R					
	S					
	Т					

## **NON-PATENT DOCUMENTS**

		NON-TATENT DOCUMENTS
*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Worhach et al, "Integration of Environmental Factors in Process Modeling for Printed Circuit Board Manufacturing, Part I: Assembly," Proceedings of the 1997 IEEE International Symposium on Electronics and the Environment, pp. 218-225 (May 1997)
	V	Varney, "Arm Your Salesforce with the Web," Datamation, Vol. 42 Issue 16, pp. 72-74 (October 1996)
	w	Przekwas et al, "A Virtual Prototyping Environment for Multi-Scale, Multi-Disciplinary Simulation of Electronics Packaging of MCMs," IEEE Inter-Society Conference on Thermal Phenomena in Electronic Systems, pp. 352-358 (May 1996)
	х	Dance et al, "Modeling the cost of ownership of assembly and inspection," IEEE Transactions on Components, Packaging, and Manufacturing TechnologyPart C, Volume 19 Issue 1, pp. 57-60 (January 1996)

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).) Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.

U.S. Patent and Trademark Office PTO-892 (Rev. 01-2001)

**Notice of References Cited** 

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